



INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification ⁷ : C25D 3/02, 17/02, 17/12, B05C 3/20		A1	(11) International Publication Number: WO 00/61837
			(43) International Publication Date: 19 October 2000 (19.10.00)
(21) International Application Number: PCT/US00/10210		(81) Designated States: CN, JP, KR, SG, US, European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE).	
(22) International Filing Date: 13 April 2000 (13.04.00)		Published With international search report.	
(30) Priority Data: 60/129,055 13 April 1999 (13.04.99) US 60/143,769 12 July 1999 (12.07.99) US 60/182,160 14 February 2000 (14.02.00) US			
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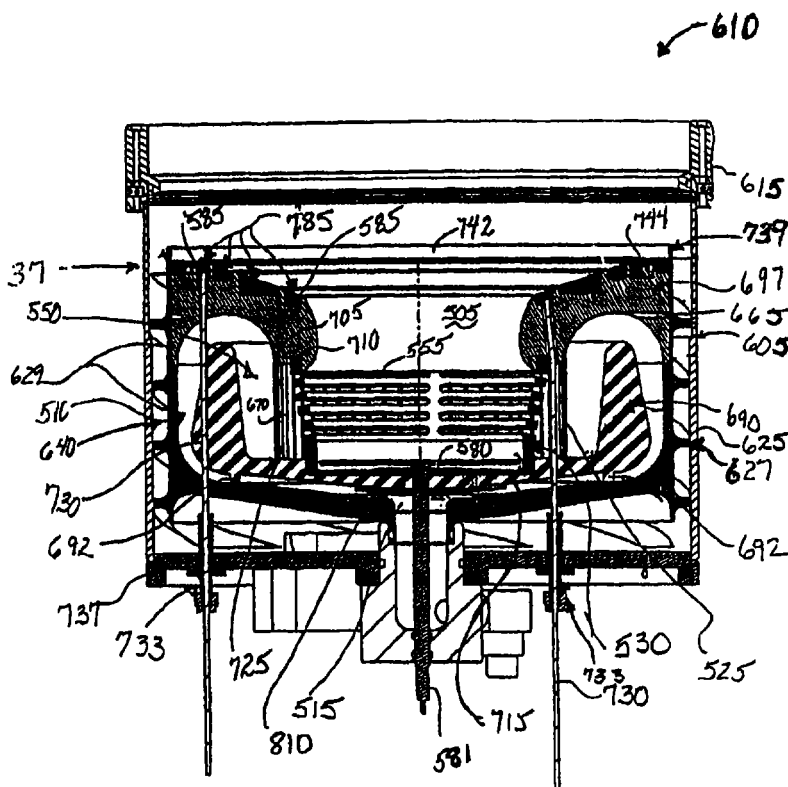


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(54) Title: WORKPIECE PROCESSOR HAVING PROCESSING CHAMBER WITH IMPROVED PROCESSING FLUID FLOW

(57) Abstract

A processing container (610) for providing a flow of a processing fluid during immersion processing of at least one surface of a microelectronic workpiece is set forth. The processing container comprises a principal fluid flow chamber (505) providing a flow of processing fluid to at least one surface of the workpiece and a plurality of nozzles (535) disposed to provide a flow of processing fluid to the principal fluid flow chamber. The plurality of nozzles are arranged and directed to provide vertical and radial fluid flow components that combine to generate a substantially uniform normal flow component radially across the surface of the workpiece. An exemplary apparatus using such a processing container is also set forth that is particularly adapted to carry out an electroplating process. In accordance with a further aspect of the present disclosure, an improved fluid removal path (640) is provided for removing fluid from a principal fluid flow chamber during immersion processing of a microelectronic workpiece.



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